

NTLJD2105L

POWER MOSFET

8 V, 4.3 A, μ Cool™ High Side Load Switch with Level Shift, 2x2 mm WDFN Package

Features

- WDFN 2x2 mm Package with Exposed Drain Pads Offers Excellent Thermal Performance
- Low $R_{DS(on)}$ P-Channel Load Switch with N-channel MOSFET for Level Shift
- N Channel Operated at 1.5 V Gate Drive Voltage Level
- P Channel Operated at 1.5 V Supply Voltage
- Same Footprint as SC88
- Low Profile (<0.8 mm) Allows it to Fit Easily into Extremely Thin Environments
- ESD Protection
- These are Pb-Free Devices

Applications

- High Slide Load Switch with Level Shift
- Optimized for Power Management in Ultra Portable Equipment

MOSFET(Q2) MAXIMUM RATINGS

($T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter			Symbol	Value	Unit
Q2 Input Voltage (V_{DS} , P-Channel)			V_{IN}	8	V
Q1 On/Off Voltage (V_{GS} , N-Channel)			$V_{ON/OFF}$	6	V
Continuous Load Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	I_L	4.3	A
		$T_A = 85^\circ\text{C}$		3.1	
Power Dissipation (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	P_D	1.56	W
Continuous Load Current (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	I_L	2.5	A
		$T_A = 85^\circ\text{C}$		1.8	
Power Dissipation (Note 2)		$T_A = 25^\circ\text{C}$	P_D	0.52	W
Pulsed Load Current	$t_p = 10 \mu\text{s}$		I_{LM}	20	A
Operating Junction and Storage Temperature			T_J, T_{STG}	-55 to 150	$^\circ\text{C}$
Source Current (Body Diode) (Note 2)			I_S	-2.7	A
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T_L	260	$^\circ\text{C}$

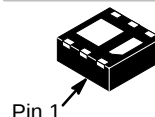
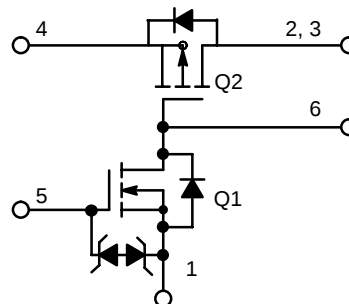
1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)
2. Surface-mounted on FR4 board using the minimum recommended pad size.



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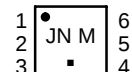
<http://onsemi.com>

V_{INMAX}	$R_{DS(on)} MAX$	$I_L MAX$
20 V	50 m Ω @ 4.5 V	4.3 A
	60 m Ω @ 2.5 V	
	80 m Ω @ 1.8 V	
	115 m Ω @ 1.5 V	



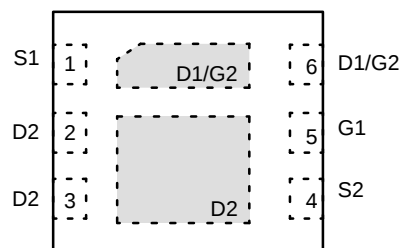
WDFN6
CASE 506AZ

MARKING DIAGRAM



JN = Specific Device Code
M = Date Code
■ = Pb-Free Package

PIN CONNECTIONS



(Top View)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	80	$^{\circ}\text{C/W}$
Junction-to-Ambient – $t \leq 5$ s (Note 3)	$R_{\theta JA}$	38	$^{\circ}\text{C/W}$
Junction-to-Ambient – Steady State Min Pad (Note 4)	$R_{\theta JA}$	180	$^{\circ}\text{C/W}$

3. Surface Mounted on FR4 Board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
 4. Surface-mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Q2 Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	-8.0			V
Q2 Forward Leakage Current	I_{FL}	$V_{ON/OFF} = 0 \text{ V}, V_{IN} = 8.0 \text{ V}$	$T_J = 25^{\circ}\text{C}$		0.1	μA
			$T_J = 85^{\circ}\text{C}$		1	
Q1 Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS1} = \pm 6 \text{ V}$			± 100	nA
Q1 Diode Forward On-Voltage	V_{SD}	$I_S = -1.0 \text{ A}, V_{GS1} = 0 \text{ V}$		-0.8	-1.1	V

ON CHARACTERISTICS

Q1 ON/OFF Voltage	$V_{ON/OFF}$		1.5		8.0	
Q1 Gate Threshold Voltage	$V_{GS1(TH)}$	$V_{GS1} = V_{DS1}, I_D = 250 \mu\text{A}$	0.40		1.0	V
Q2 Input Voltage	V_{IN}		1.8		8.0	V
Q2 Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{IN} = 4.5 \text{ V}, I_L = 4.0 \text{ A}$		33	50	m Ω
		$V_{IN} = 2.5 \text{ V}, I_L = 3.0 \text{ A}$		40	60	
		$V_{IN} = 1.8 \text{ V}, I_L = 1.7 \text{ A}$		60	80	
		$V_{IN} = 1.5 \text{ V}, I_L = 1.2 \text{ A}$		75	115	
Q2 Load Current	I_L	$V_{DROP} \leq 0.2 \text{ V}, V_{IN} = 2.5 \text{ V}, V_{ON/OFF} = 1.5 \text{ V}$	1.0			A
		$V_{DROP} \leq 0.3 \text{ V}, V_{IN} = 1.8 \text{ V}, V_{ON/OFF} = 1.5 \text{ V}$	1.0			

TYPICAL PERFORMANCE CURVES ($T_J = 25^\circ\text{C}$ unless otherwise noted)

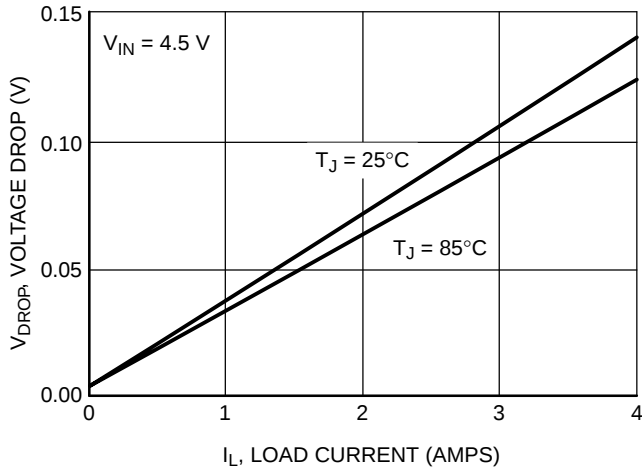


Figure 1. Voltage Drop versus Load Current @ $V_{IN} = 4.5\text{ V}$

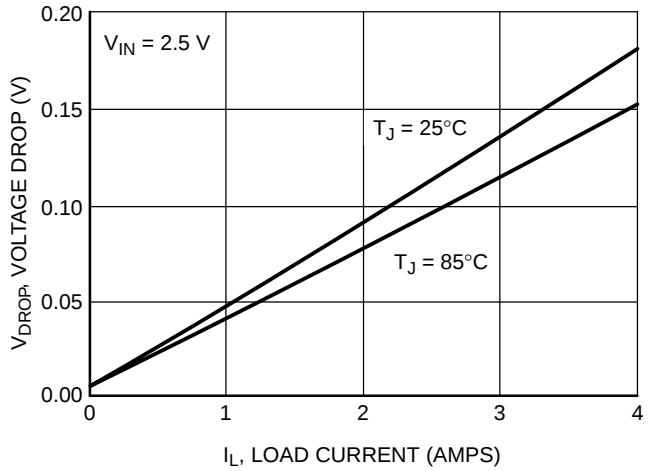


Figure 2. Voltage Drop versus Load Current @ $V_{IN} = 2.5\text{ V}$

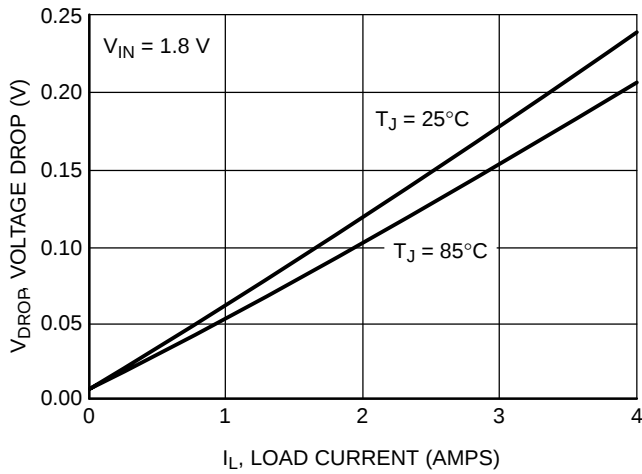


Figure 3. Voltage Drop versus Load Current @ $V_{IN} = 1.8\text{ V}$

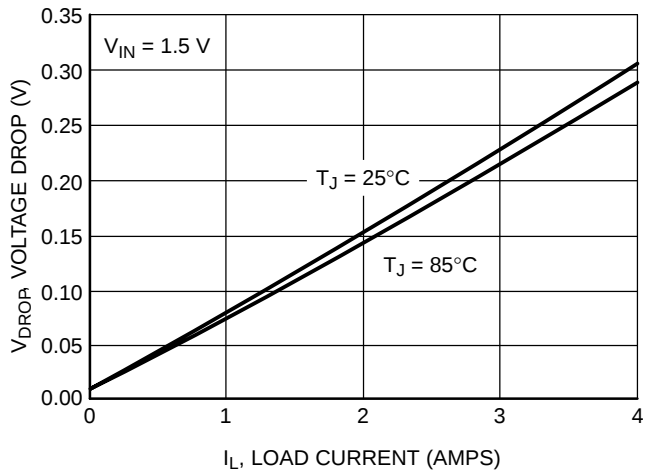


Figure 4. Voltage Drop versus Load Current @ $V_{IN} = 1.5\text{ V}$

TYPICAL PERFORMANCE CURVES ($T_J = 25^\circ\text{C}$ unless otherwise noted)

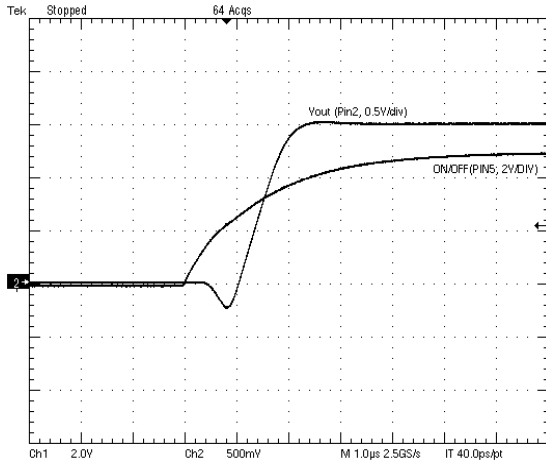


Figure 5. Turn-on
($V_{in} = 1.5\text{ V}$, $R_L = 3\ \Omega$, $R_1 = 1\text{ k}\Omega$, $R_2 = 0$, $C_1 = 47\text{ nF}$)

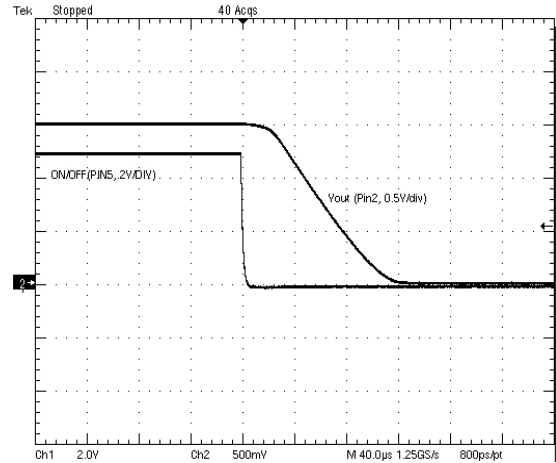


Figure 6. Turn-off
($V_{in} = 1.5\text{ V}$, $R_L = 3\ \Omega$, $R_1 = 1\text{ k}\Omega$, $R_2 = 0$, $C_1 = 47\text{ nF}$)

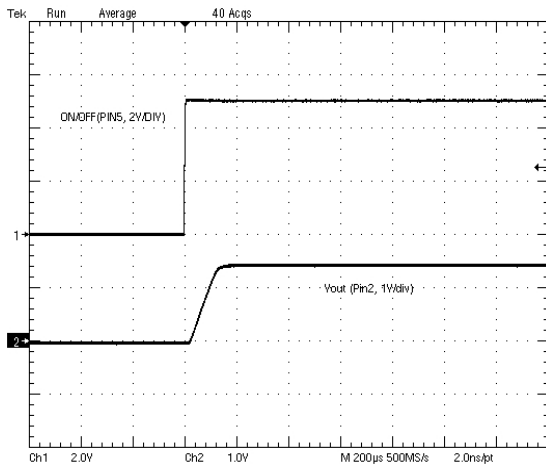


Figure 7. Turn-on
($V_{in} = 1.5\text{ V}$, $R_L = 3\ \Omega$, $R_1 = 10\text{ k}\Omega$, $R_2 = 1\text{ k}\Omega$, $C_1 = 47\text{ nF}$)

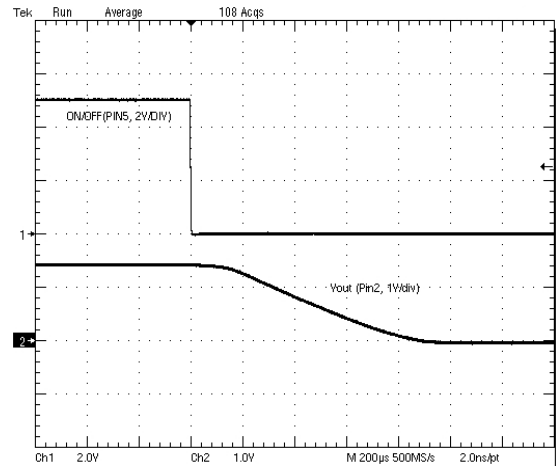


Figure 8. Turn-off
($V_{in} = 1.5\text{ V}$, $R_L = 3\ \Omega$, $R_1 = 10\text{ k}\Omega$, $R_2 = 1\text{ k}\Omega$, $C_1 = 47\text{ nF}$)

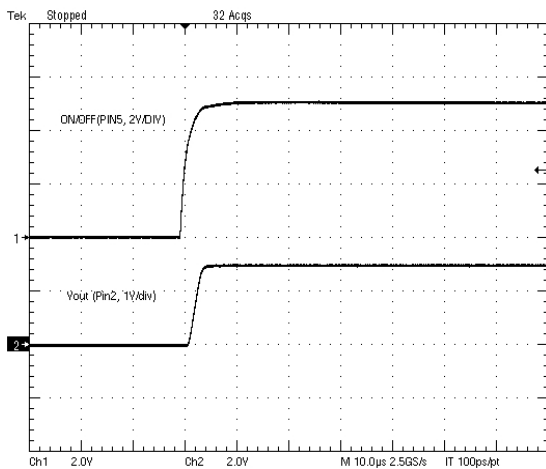


Figure 9. Turn-on
($V_{in} = 3\text{ V}$, $R_L = 3\ \Omega$, $R_1 = 10\text{ k}\Omega$, $R_2 = 1\text{ k}\Omega$, $C_1 = 47\text{ nF}$)

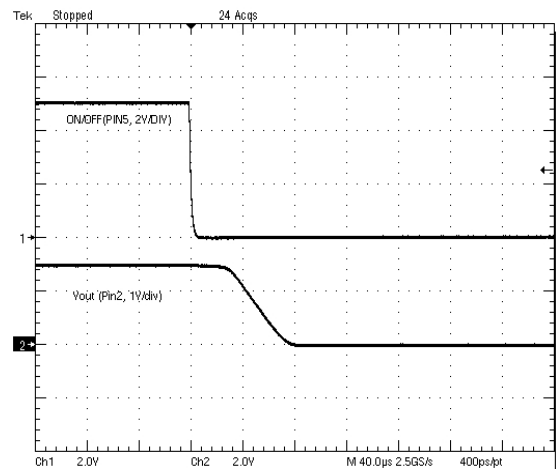


Figure 10. Turn-off
($V_{in} = 3\text{ V}$, $R_L = 3\ \Omega$, $R_1 = 10\text{ k}\Omega$, $R_2 = 1\text{ k}\Omega$, $C_1 = 47\text{ nF}$)

NTLJD2105L

TYPICAL PERFORMANCE CURVES ($T_J = 25^\circ\text{C}$ unless otherwise noted)

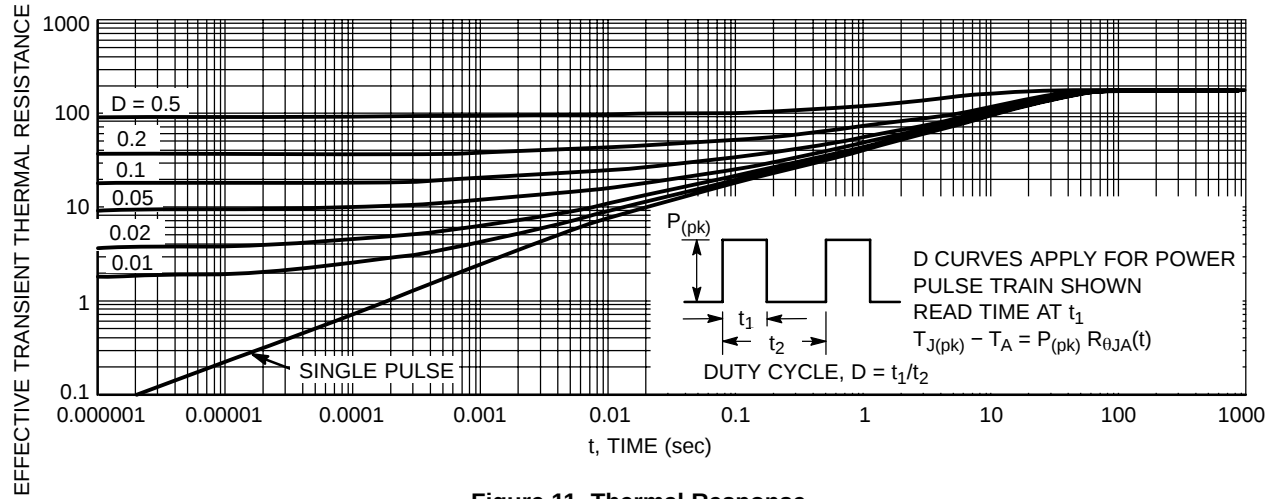


Figure 11. Thermal Response

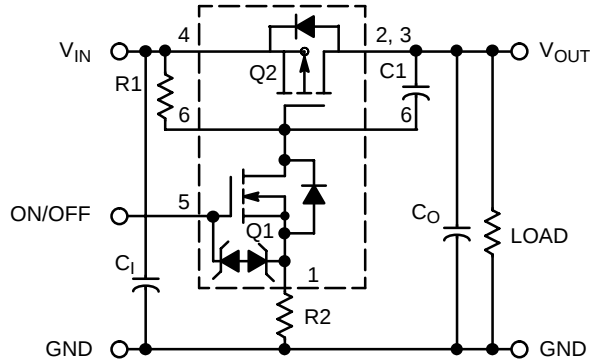


Figure 12. Load Switch Application

Components	Description	Value
R1	Pull-up Resistor	Typical 10 k Ω to 1.0 Ω *
R2	Optional Slew-Rate Control	Typical 0 k Ω to 100 k Ω *
C_O, C_I	Output Capacitance	Usually < 1.0 μF
C1	Optional In-Rush Current Control	Typical ≤ 1000 pF

*Minimum R1 value should be at least 10 x R2 to ensure Q1 turn-on.

ORDERING INFORMATION

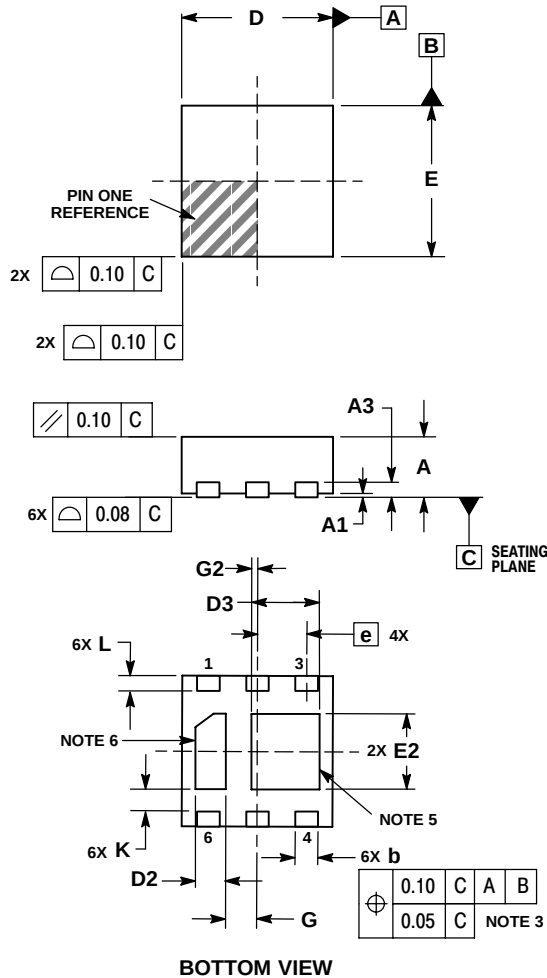
Device	Package	Shipping [†]
NTLJD2105LTBG	WDFN6 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NTLJD2105L

PACKAGE DIMENSIONS

WDFN6, 2x2
CASE 506AZ-01
ISSUE A

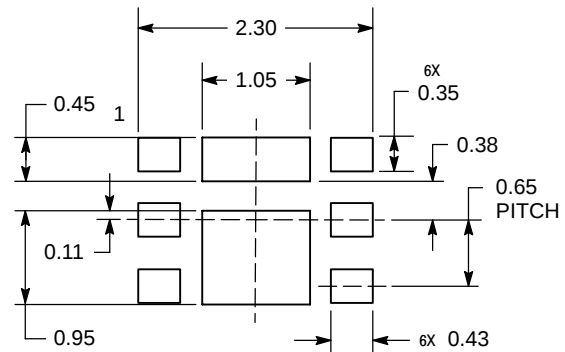


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. PINS 2 & 3 CONNECTED TO LARGE FLAG.
6. PIN 6 CONNECTED TO SMALL FLAG.

MILLIMETERS		
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.25	0.35
D	2.00	BSC
D2	0.30	0.50
D3	0.80	1.00
E	2.00	BSC
E2	0.90	1.10
e	0.65	BSC
G	0.41	REF
G2	0.085	REF
K	0.25	REF
L	0.20	0.30

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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